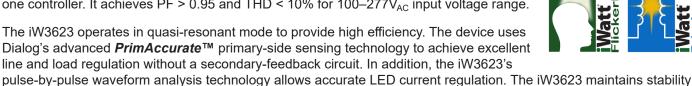


#### 1 Description

The iW3623 is a high-performance AC/DC off-line power supply controller for LED luminaires. The iW3623 combines power factor correction and LED current regulation into one controller. It achieves PF > 0.95 and THD < 10% for  $100-277V_{AC}$  input voltage range.

over all operating conditions without the need for loop compensation components.





#### 2 Features

- Isolated AC/DC off-line LED driver
- Power factor > 0.95 for wide input voltage range  $100 - 277V_{AC}$
- Total harmonic distortion (THD) < 10%
- Under 5% 100Hz/120Hz output current ripple
- Resonant control to achieve high efficiency
- LED current foldback with external NTC
- Small size design
  - Small size input bulk capacitor
  - Small size output capacitor
  - Small transformer

- *PrimAccurate*™ primary-side sensing eliminates the need for optocoupler feedback and simplifies design
- Tight LED current regulation ± 5%
- Under 0.5 second start-up time
- Hot-plug LED module support
- Multiple protection features:
  - » LED open circuit protection
  - Single-fault protection
  - Over-current protection
  - LED short-circuit protection
  - Current sense-resistor-short-circuit protection
  - Input over-voltage and brown-out protection

#### 3 Applications

- Non-dimmable LED lamps and luminaires
- Optimized for up to 45W output power





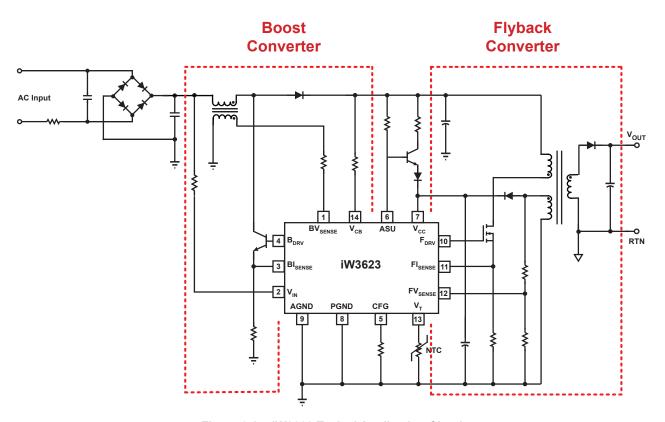


Figure 3.1: iW3623 Typical Application Circuit



# **4 Pinout Description**

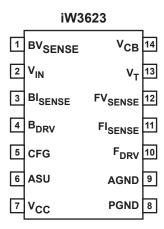


Figure 4.1: 14-Lead SOIC Package

| Pin Number | Pin Name            | Туре          | Pin Description   |
|------------|---------------------|---------------|---|
| 1          | BV <sub>SENSE</sub> | Analog Input  | Boost inductor voltage feedback   |
| 2          | V <sub>IN</sub>     | Analog Input  | Rectified AC line voltage feedback  |
| 3          | BI <sub>SENSE</sub> | Analog Input  | Boost current sense (used for cycle-by-cycle peak current limit)  |
| 4          | B <sub>DRV</sub>    | Output        | Base drive for boost BJT  |
| 5          | CFG                 | Analog In/Out | Chooses input start-up voltage and brown-out shutdown voltage   |
| 6          | ASU                 | Output        | Active start-up control   |
| 7          | V <sub>cc</sub>     | Power         | Power supply for control logic and voltage sense for power-on reset circuitry. A decoupling capacitor of $0.1\mu F$ or so should be connected between the $V_{CC}$ pin and GND. |
| 8          | PGND                | Ground        | Power ground  |
| 9          | AGND                | Ground        | Signal ground   |
| 10         | F <sub>DRV</sub>    | Output        | Gate drive for flyback MOSFET   |
| 11         | FI <sub>SENSE</sub> | Analog Input  | Primary current sense (used for cycle-by-cycle peak current control and limit)  |
| 12         | FV <sub>SENSE</sub> | Analog Input  | Auxiliary voltage sense (used for primary-side regulation and ZVS)  |
| 13         | V <sub>T</sub>      | Analog Input  | Output power limit and shutdown control   |
| 14         | V <sub>CB</sub>     | Analog Input  | Boost output voltage feedback   |



### **5 Absolute Maximum Ratings**

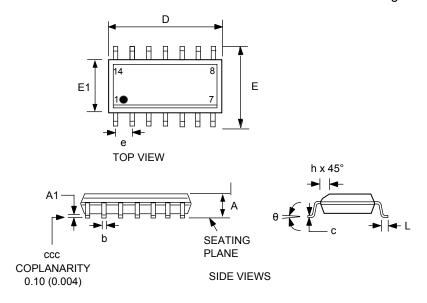
Absolute maximum ratings are the parameter values or ranges which can cause permanent damage if exceeded.

| Parameter  | Symbol            | Value       | Units |
|--|-------------------|-------------|-------|
| DC supply voltage range (pin 7)                              | V <sub>cc</sub>   | -0.3 to 18  | V     |
| F <sub>DRV</sub> output (pin 10)                             |                   | -0.3 to 18  | V     |
| B <sub>DRV</sub> output (pin 4)                              |                   | -0.3 to 4.0 | V     |
| CFG input (pin 5)  |                   | -0.3 to 4.0 | V     |
| CFG output (pin 5)   |                   | -0.3 to 18  | V     |
| FV <sub>SENSE</sub> input (pin 12, I ≤ 10mA)                 |                   | -0.7 to 4.0 | V     |
| BV <sub>SENSE</sub> input (pin 1, I ≤ 3mA)                   |                   | -0.7 to 4.0 | V     |
| V <sub>IN</sub> input (pin 2)                                |                   | -0.3 to 18  | V     |
| V <sub>CB</sub> input (pin 14)                               |                   | -0.3 to 18  | V     |
| FI <sub>SENSE</sub> input (pin 11)                           |                   | -0.3 to 4.0 | V     |
| BI <sub>SENSE</sub> input (pin 3)                            |                   | -0.3 to 4.0 | V     |
| ASU output (pin 6)   |                   | -0.3 to 18  | V     |
| V <sub>T</sub> input (pin 13)                                |                   | -0.3 to 4.0 | V     |
| Maximum junction temperature                                 | T <sub>JMAX</sub> | 150         | °C    |
| Operating junction temperature                               | T <sub>JOPT</sub> | -40 to 150  | °C    |
| Storage temperature  | T <sub>STG</sub>  | -65 to 150  | °C    |
| Thermal Resistance Junction-to-PCB Board Surface Temperature | ΨЈВ               | 45          | °C/W  |
| ESD rating per JEDEC JESD22-A114                             |                   | ±2,000      | V     |
| Latch-up test per JESD78A                                    |                   | ±100        | mA    |



#### **6 Physical Dimensions**

#### 14-Lead SOIC Package



| Symbol | Inc   | hes   | Millimeters |      |  |
|--------|-------|-------|-------------|------|--|
| Syr    | MIN   | MAX   | MIN         | MAX  |  |
| Α      | 0.053 | 0.069 | 1.35        | 1.75 |  |
| A1     | 0.004 | 0.010 | 0.10        | 0.25 |  |
| b      | 0.013 | 0.020 | 0.33        | 0.51 |  |
| С      | 0.007 | 0.010 | 0.19        | 0.25 |  |
| D      | 0.337 | 0.344 | 8.55        | 8.75 |  |
| E1     | 0.150 | 0.157 | 3.80        | 4.00 |  |
| Е      | 0.228 | 0.244 | 5.80        | 6.20 |  |
| е      | 0.050 | BSC   | 1.27 BSC    |      |  |
| L      | 0.016 | 0.050 | 0.40        | 1.27 |  |
| h      | 0.010 | 0.020 | 0.25        | 0.50 |  |
| θ      | 0°    | 8°    | 0°          | 8°   |  |
| ССС    | 0.0   | 04    | 0.10        |      |  |

Compliant to JEDEC Standard MS12F

Controlling dimensions are in inches; millimeter dimensions are for reference only

This product is RoHS compliant and Halide free.

Soldering Temperature Resistance:

- [a] Package is IPC/JEDEC Std 020D Moisture Sensitivity Level 1
- [b] Package exceeds JEDEC Std No. 22-A111 for Solder Immersion Resistance; package can withstand 10 s immersion < 260°C

Dimension D does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 mm per end. Dimension E does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 mm per side.

The package top may be smaller than the package bottom. Dimensions D and E are determined at the outermost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.

Figure 6.1: 14-Lead SOIC Package

#### 7 Ordering Information

| Part no.  | Options | Package | Description              |
|-----------|---------|---------|--------------------------|
| iW3623-00 |         | SOIC-14 | Tape & Reel <sup>1</sup> |

Note 1: Tape & Reel packing quantity is 2,500/reel. Minimum ordering quantity is 2,500.



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(Rev.1.0 Mar 2020)

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